DSC2G03

Silicon NPN epitaxial planar type

For high-frequency amplification

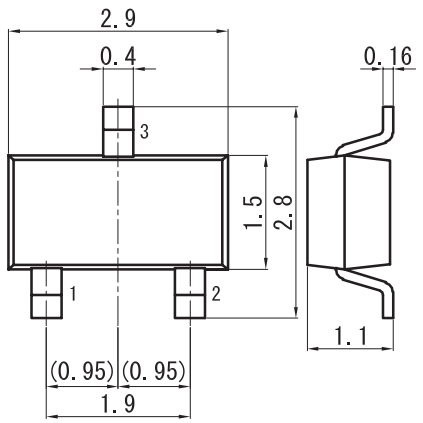
■ Features

- High transition frequency f_T
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: C6

■ Packaging

DSC2G03×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



1: Base
2: Emitter
3: Collector

Panasonic	Mini3-G3-B
JEITA	SC-59A
Code	TO-236AA/SOT-23

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	30	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-base voltage (Collector open)	V_{EBO}	3	V
Collector current	I_C	50	mA
Collector power dissipation	P_C	200	mW
Junction temperature	T_j	150	°C
Operating ambient temperature	T_{opr}	–40 to +85	°C
Storage temperature	T_{stg}	–55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 100\ \mu A$, $I_E = 0$	30			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10\ \mu A$, $I_C = 0$	3			V
Base-emitter voltage	V_{BE}	$V_{CE} = 10$ V, $I_C = 2$ mA		740		mV
Forward current transfer ratio	h_{FE}	$V_{CE} = 10$ V, $I_C = 2$ mA	25		250	—
Transition frequency *1, 2	f_T	$V_{CE} = 10$ V, $I_C = 15$ mA	800		1 600	MHz
Reverse transfer capacitance (Common emitter)	C_{re}	$V_{CE} = 10$ V, $I_C = 1$ mA , f = 10.7 MHz		0.9		pF
Reverse transfer capacitance (Common base)	C_{rb}	$V_{CB} = 6$ V, $I_C = 0$, f = 1 MHz		0.7		pF
Power gain	PG	$V_{CE} = 10$ V, $I_C = 1$ mA , f = 200 MHz		20		dB

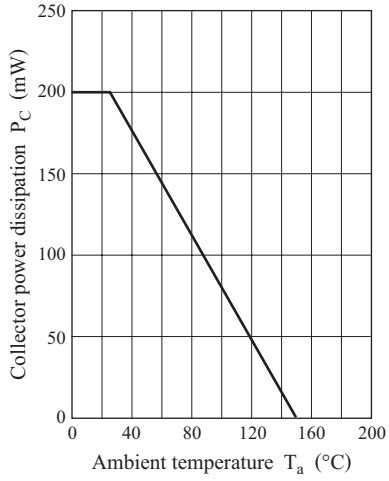
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. ∗1: Pulse measurement
   ∗2: Rank classification

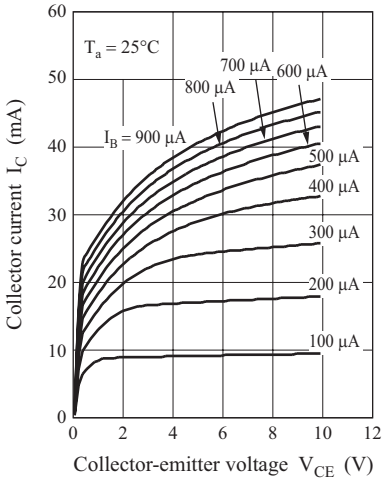
Code	T	S	0
Rank	T	S	No-rank
f_T	800 to 1 400	1 000 to 1 600	800 to 1 600
Marking Symbol	C6T	C6S	C6

Product of no-rank is not classified and have no marking symbol for rank.

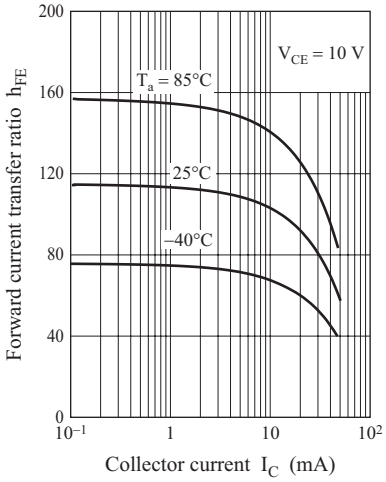
P_C — T_a



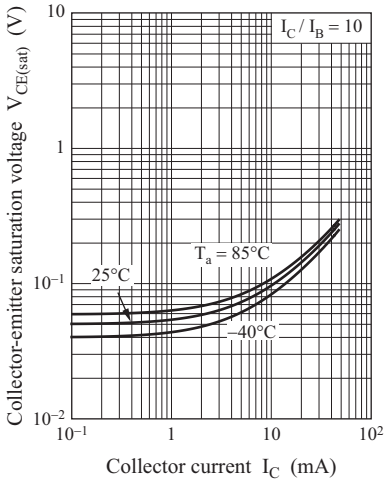
I_C — V_{CE}



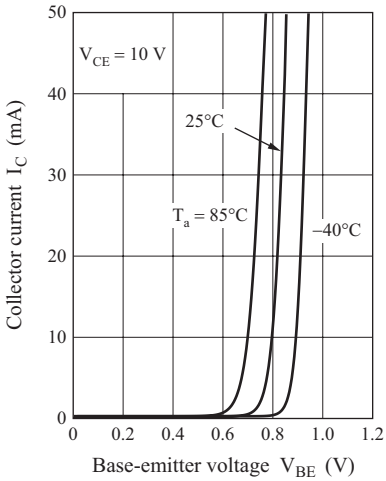
h_{FE} — I_C



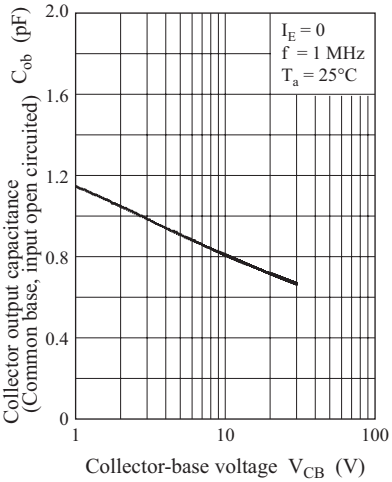
$V_{CE(sat)}$ — I_C



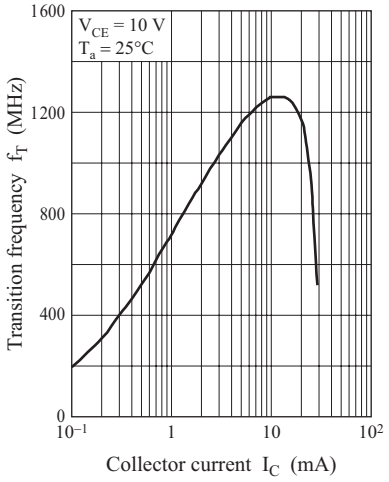
I_C — V_{BE}



C_{ob} — V_{CB}

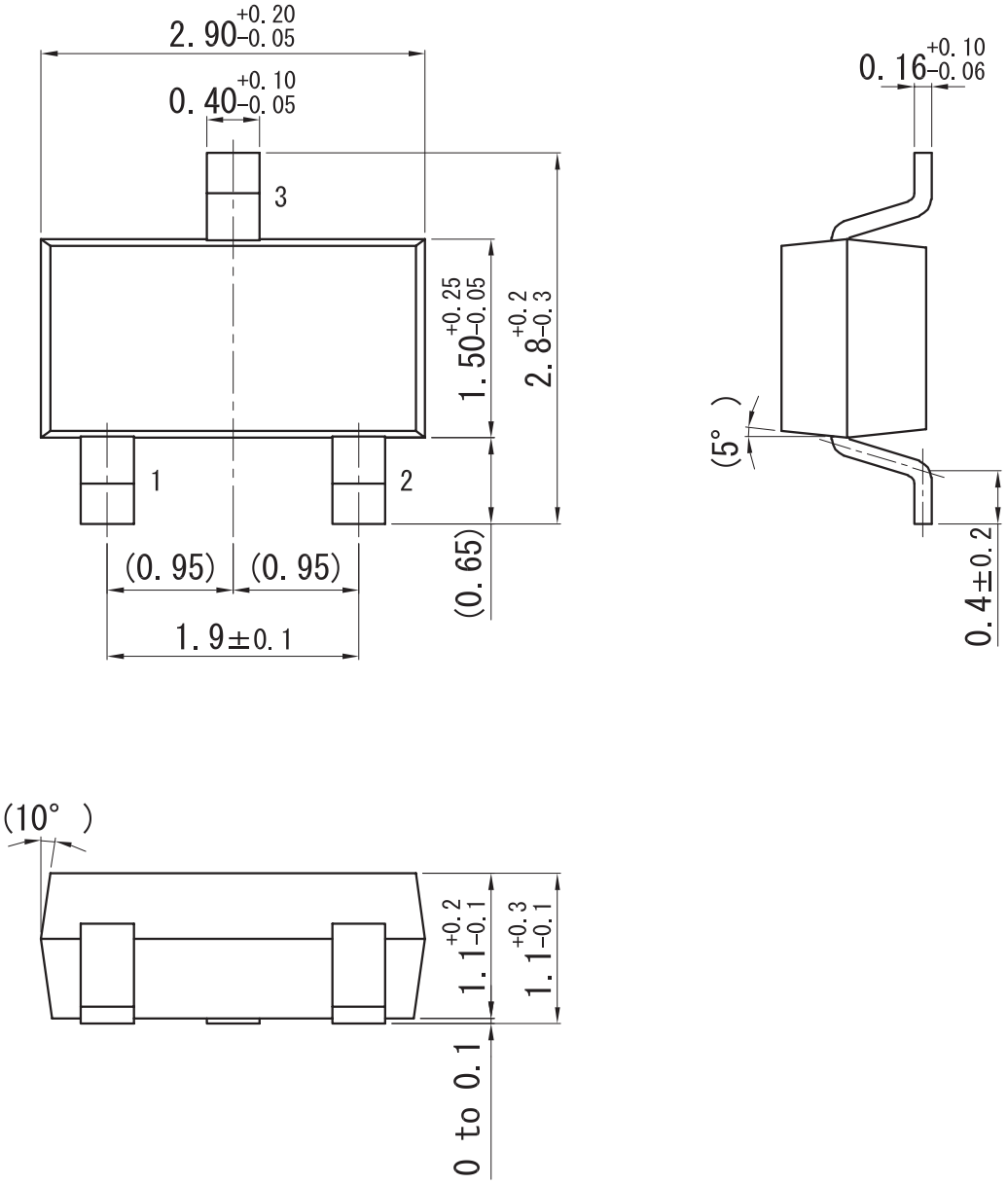


f_T — I_C

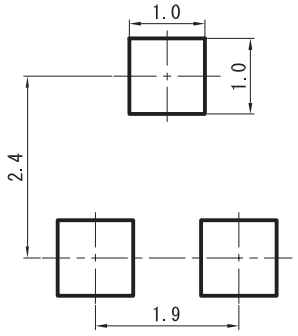


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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